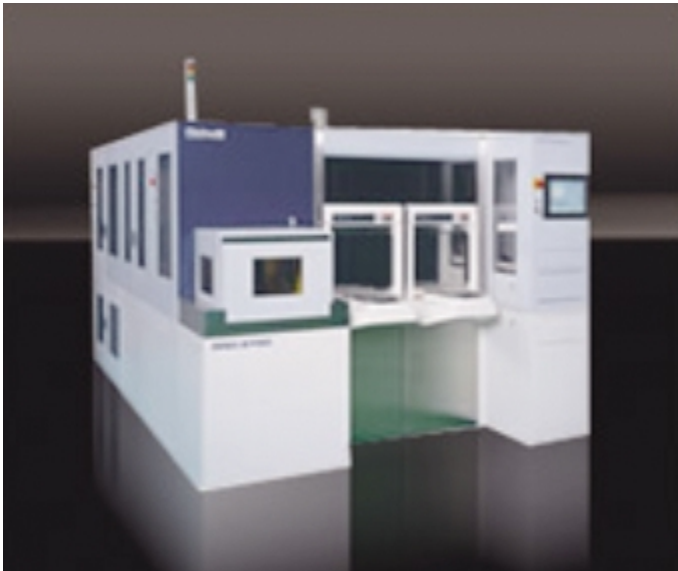


300mm Fully-Automatic Multifunction Wafer Mounter

RAD-2700F/12S_a



Outline

–Fully-automatic wafer mounter suited for 300mm thin wafer manufacturing, with the following functions:

- UV irradiation to BG Tape
- Alignment
- Single DAF lamination
- Single DAF post curing
- Wafer mounting
- BG Tape peeling

–Ability to operate in-line with DISCO Corporation's DFG8000 series back grinder or DGP8000 series grinder/polisher.

–Corresponds to DBG process.

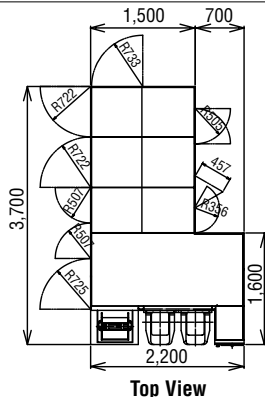
Options

- Host Communication Function (Communication Format : Conforms to SECS-I and HSMS/Software : Conforms to GEM)
- Vision System (Wafer ID Reader & Barcode Attachment System)
- Dicing Tape In-line Pre-cutting
- DBG Process Compatibility
- In-line Operation with DISCO Corporation DFG8000 series or DGP8000 series
- RFID Traceability System

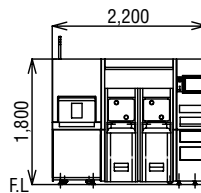
Suitable Tapes

- Dicing tape : Adwill D series, G series
- Dicing die bonding tape : Adwill LE Tape

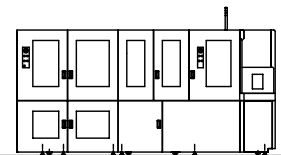
External View



Top View



Front View



Left Side View

Unit:mm

Facility

Power Supply	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
Air Supply	Power consumption	: 10.0kW (AC200V)
	Air pressure	: 0.5-0.8MPa
	Air consumption	: >400L/min (ANR)
Vacuum Supply	Vacuum pressure	: >-80kPa

Applicable Wafer Size 200mm, 300mm

Size
Width : 2,200mm
Depth : 3,700mm
Height : 1,800mm
(excluding the signal tower and protruding parts)

Weight 2,900kg

UPH

Single DAF lamination system is disabled : 25wafers/hour
Single DAF lamination system is enabled (post-curing time= 0sec) : 20wafers/hour
Single DAF lamination system is enabled (post-curing time= 60sec) : 15wafers/hour

The above processing capacity is based on following conditions ("stand-alone"):

Wafer : 300mm diameter non-polished mirror wafer
Ring frame : for 300mm wafer
Dicing tape : G-18 from LINTEC
Back grinding tape : E-6142S from LINTEC



LINTEC Corporation *Linking your dreams*

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